



**Device** = VS1003B  
**Package** = 48L LQFP 7x7x1.4 mm  
**REF DOC** = BF43431 rev B

Document: A  
 Rev: 3.0  
 Marking on device:

**VS1003B**  
**PPPPPPPPPP**  
**YYWW**

where, P P P P P P P P P P = Lot ID  
 Y Y W W = assembly Year and Week > 1011

no	Part Name	Material Name	Component WT (mg)	Material Content (Element)	CAS#	Element Wt (%)	Element WT (mg)	WT% of total unit Wt	ppm
1	Die	Silicon Chip	14.217	Silicon	7440-21-3	100.00	14.217	7.682	76821.242
2	Lead Frame	Spot Ag Copper (Olin C7025)	79.408	Copper	7440-50-8	96.200	74.834	40.436	404363.741
				Ni	7440-02-0	3.000	2.334	1.261	12610.096
				Si	7440-21-3	0.650	0.506	0.273	2732.187
				Mg	7439-95-4	0.150	0.117	0.063	630.505
				Silver	7440-22-4		1.618	0.874	8742.827
3	Mold Compound	G700LX	86.394	Silica Fused	60676-86-0	81.500	70.411	38.046	380464.861
				Epoxy Resin	Trade Secret	10.000	8.639	4.668	46682.805
				Phenol Resin	Trade Secret	8.000	6.912	3.735	37346.244
				Carbon Black	1333-86-4	0.500	0.432	0.233	2334.140
4	Gold Wire	Gold (1.0 mils)	0.704	Au	7440-57-5	99.990	0.704	0.380	3803.668
				Dopant	-	0.010	0.000	0.000	0.380
5	Die Attach Material	CRM 1076 NS	1.443	Silver (Ag)	7440-22-4	82.000	1.183	0.639	6393.719
				Epoxy resin	9003-36-5	10.000	0.144	0.078	779.722
				Diluent	Trade Secret	2.000	0.029	0.016	155.944
				Dicyandiamide	461-58-5	0.900	0.013	0.007	70.175
				Hardener	Trade Secret	5.100	0.074	0.040	397.658
6	Solder	Sn 100	2.900	Sn	7440-31-5	99.987	2.900	1.567	15668.048
				Pb	7439-92-1	0.005	0.000	0.000	0.784
				Cu	7440-50-8	0.003	0.000	0.000	0.470
				Cd	7440-43-9	0.001	0.000	0.000	0.157
				Bi	7440-69-9	0.003	0.000	0.000	0.470
				Sb	7440-36-0	0.001	0.000	0.000	0.157
Total Unit Weight =			185.066						100.000